

INTEGRATED LDO WITH SWITCHOVER CIRCUIT FOR NOTEBOOK COMPUTERS

FEATURES

- Wide Input Voltage Range: 4.5 V to 28 V
- 5-V/3.3-V, 100-mA, LDO Output
- Glitch Free Switch Over Circuit
- *Always-On* 3.3-V, 5-mA LDO Output for RTC
- 250 kHz Clock Output for Charge Pump
- Thermal Shutdown (Non-latch)
- 10Ld QFN (DRC) Package

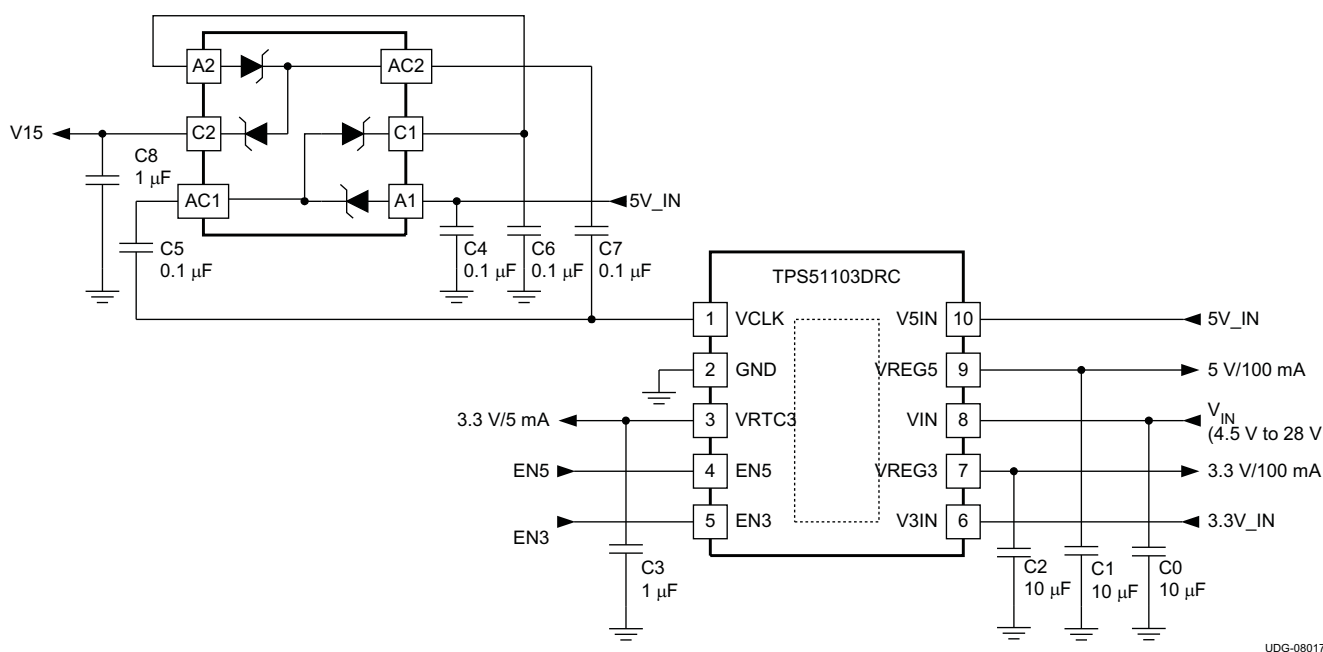
APPLICATIONS

- Notebook Computers
- Mobile Digital Consumer Products

DESCRIPTION

The TPS51103 integrates three LDOs. The 5-V and 3.3-V LDOs are both rated at 100 mA and also include a glitch-free switch-over feature allowing for optimized battery life. An additional 3.3-V LDO is designed to provide an *always on* power output for the real time clock (RTC). The TPS51103 integrates a clock output to use with an external charge pump. The TPS51103 offers an innovative solution for optimizing the complex and multiple power rails typically found in a Notebook Computer. The TPS51103 is available in the 10-pin QFN package and is specified from -40°C to 85°C .

TYPICAL APPLICATION CIRCUIT



UDG-08017



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

T _A	PACKAGE	PART NUMBER	TAPE & REEL QUANTITY	ECO-PLAN
–40°C to 85°C	Plastic DRC ⁽¹⁾	TPS51103DRCT	250	Green (RoHS and No Sb/Br)
		TPS51103DRCR	3000	

(1) For the most current package and ordering information, see the *Package Option Addendum* at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		VALUE	UNIT
Input voltage range ⁽²⁾	V _{IN}	–0.3 to 30	V
	EN3, EN5, V3IN	–0.3 to 6	
	V5IN	–0.3 to 6	
	V5IN, (V _{VIN} < 5.7 V)	–0.3 to V _{VIN} + 0.3	
Output voltage range ⁽²⁾	VRTC3, VCLK, VREG3, VREG5	–0.3 to 6	
Junction temperature, T _J		150	°C
Storage temperature, T _{st}		–55 to 150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to the network ground terminal unless otherwise noted.

DISSIPATION RATINGS⁽¹⁾

PACKAGE	POWER RATING BELOW AND AT T _A = 25°C	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING
10-pin DRC	1.256 W	12.6 mW/°C	0.502 W

(1) θ_{JA} (junction to air) for high-K board in still air environment is 80°C/W.

RECOMMENDED OPERATING CONDITIONS

		MIN	TYP	MAX	UNIT
Input voltage range	V _{IN}	4.5		28	V
	EN5, EN3, V3IN	–0.1		5.5	
	V5IN	–0.1		5.5	
	V5IN, (V _{VIN} < 5.5 V)	–0.1		V _{VIN}	
Output voltage range	VCLK, VRTC3, VREG3, VREG5	–0.1		5.5	
Operating free-air temperature, T _A		–40		85	°C

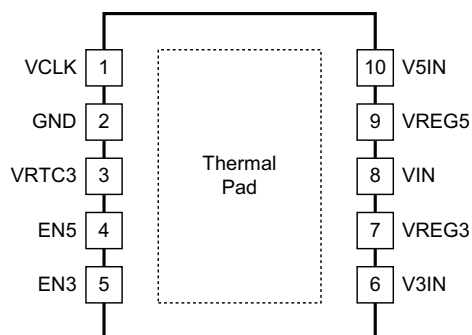
ELECTRICAL CHARACTERISTICS

over recommended free-air temperature range, $V_{VIN}=12\text{ V}$, (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY CURRENT						
I _{VIN}	VIN supply current	I _{VIN} current, T _A = 25°C, No Load, V _{EN3} =V _{EN5} =5 V, V _{V5IN} = V _{V3IN} = 0 V		35	50	μA
I _{VINSTBY}	VIN standby current	I _{VIN} current, T _A = 25°C, No Load, V _{EN3} =V _{EN5} = 0 V, V _{V5IN} = V _{V3IN} = 0 V		7	20	μA
VRTC3 OUTPUT						
V _{VRTC3}	VRTC3 output voltage	I _{VRTC3} = 1 mA, T _A = 25°C	3.27	3.32	3.37	V
		0 A < I _{VRTC3} < 5 mA, 5.5 V < V _{VIN} < 28 V	3.17		3.43	
		0 A < I _{VRTC3} < 5 mA, 4.5 V < V _{VIN} ≤ 5.5 V	3.15		3.43	
I _{VRTC3}	VRTC3 output current	V _{VRTC3} = 2 V	5	10	15	mA
VREG5 OUTPUT						
V _{VREG5}	VREG5 output voltage	V _{V5IN} = 0 V, I _{VREG5} = 1 mA, T _A = 25°C	4.95	5.05	5.15	V
		V _{V5IN} = 0 V, 10 μA < I _{VREG5} < 100 mA, 6.5V < V _{VIN} < 28 V	4.80		5.20	
		V _{V5IN} = 0 V, 0 A ≤ I _{VREG5} < 50 mA, 5.5V < V _{VIN} < 28V	4.75		5.25	
V _{VREG5DO}	VREG5 drop out voltage	V _{V5IN} = 0 V, I _{VREG5} = 50 mA, V _{VREG5} = 4.5 V		400	750	mV
I _{VREG5}	VREG5 output current	V _{V5IN} = 0 V, V _{VREG5} = 4.5 V	100	160	250	mA
V _{TH5VSW}	Switch ovethreshold	Turns on	4.45	4.65	4.80	V
		Hysteresis	25	50	75	mV
R _{5VSW}	5V SW R _{DS(on)}	V _{V5IN} = 5 V, I _{VREG5} = 100 mA		1		Ω
Td ₅	Delay for 5V SW	Turns on		1		ms
VREG3 OUTPUT						
V _{VREG3}	VREG3 output voltage	V _{V3IN} =0 V, I _{VREG3} = 1 mA, T _A = 25°C	3.23	3.33	3.37	V
		V _{V3IN} =0 V, 10 μA < I _{VREG3} < 100 mA, 6.5 V < V _{VIN} < 28 V	3.17		3.43	
		V _{V3IN} = 0V, 0A < I _{VREG3} < 50 mA, 5.5 V < V _{VIN} < 28 V	3.14		3.47	
		V _{V3IN} = 0V, 0A < I _{VREG3} < 50 mA, 4.5 V < V _{VIN} ≤ 5.5 V	3.00		3.47	
I _{VREG3}	VREG3 output current	V _{V3IN} = 0V, V _{VREG3} = 3 V	100	150	250	mA
V _{TH3VSW}	Switchover threshold	Turns on	2.95	3.07	3.17	V
		Hysteresis	20	35	50	mV
R _{3VSW}	3V SW R _{DS(on)}	V _{V3IN} = 3.3 V, I _{VREG5} = 100 mA		1.5		Ω
Td ₃	Delay for 3V SW	Turns on		1		ms
LOGIC THRESHOLD						
V _{THEN}	EN3, EN5 threshold	Enable		1.05	2.0	V
		Shutdown	0.3	0.7		
I _{EN3,5}	EN3, EN5 pulldown current	V _{EN3} = 3 V, V _{EN5} = 3 V	0.5	1.5	3.0	μA
VCLK OUTPUT						
f _{VCLK}	Clock frequency	T _A = 25°C	200	250	320	kHz
R _{VCLK}	Driver impedance	V5IN to VCLK, I _{VCLK} = 10 mA		6	15	Ω
		VCLK to GND, I _{VCLK} = 10 mA		4	15	
V _{THV5IN}	V5IN threshold	VCLK on	1.5	2.0	2.5	V
		Hysteresis		0.3		
THERMAL SHUTDOWN						
TSDN	Thermal SDN threshold	Shutdown temperature ⁽¹⁾		150		°C
		Hysteresis ⁽¹⁾		20		

(1) Ensured by design. Not production tested.

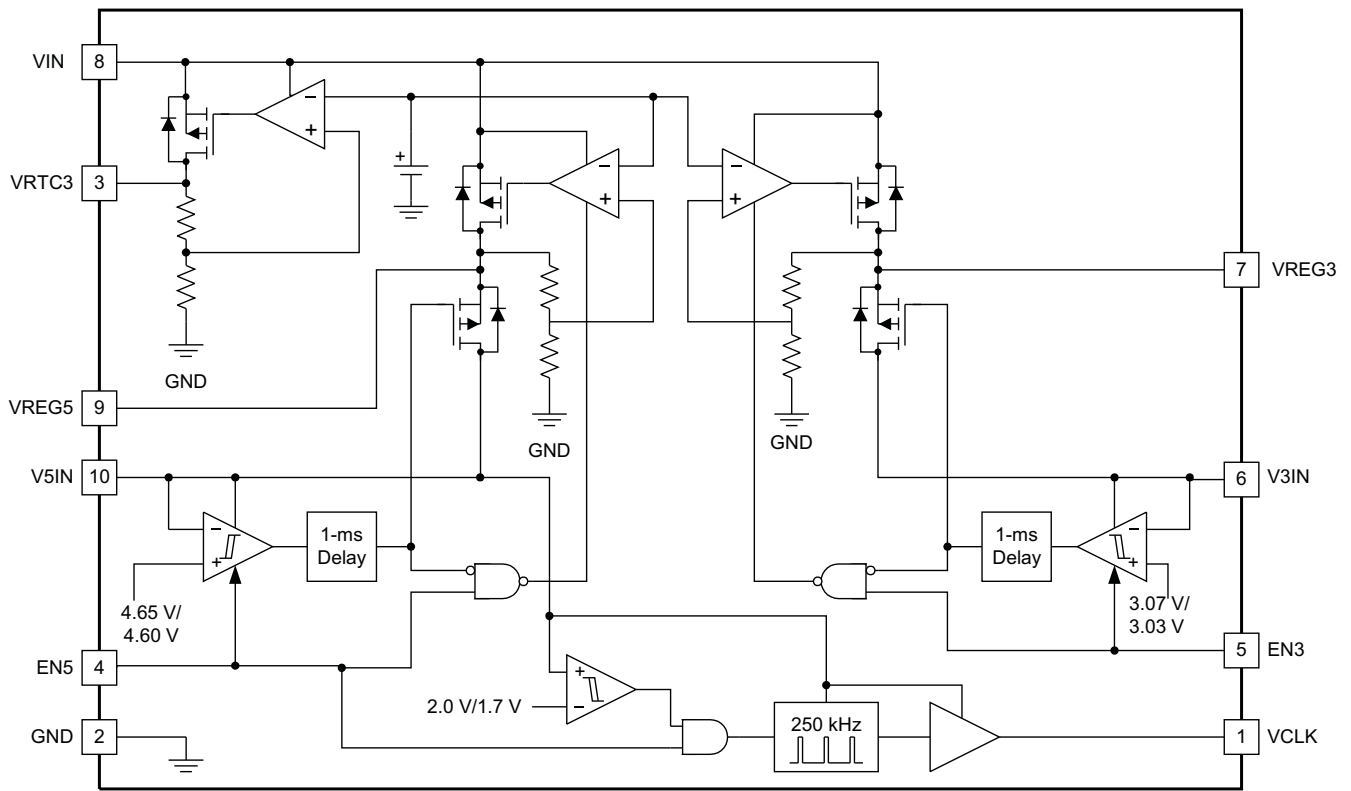
DRC PACKAGE (Top View)

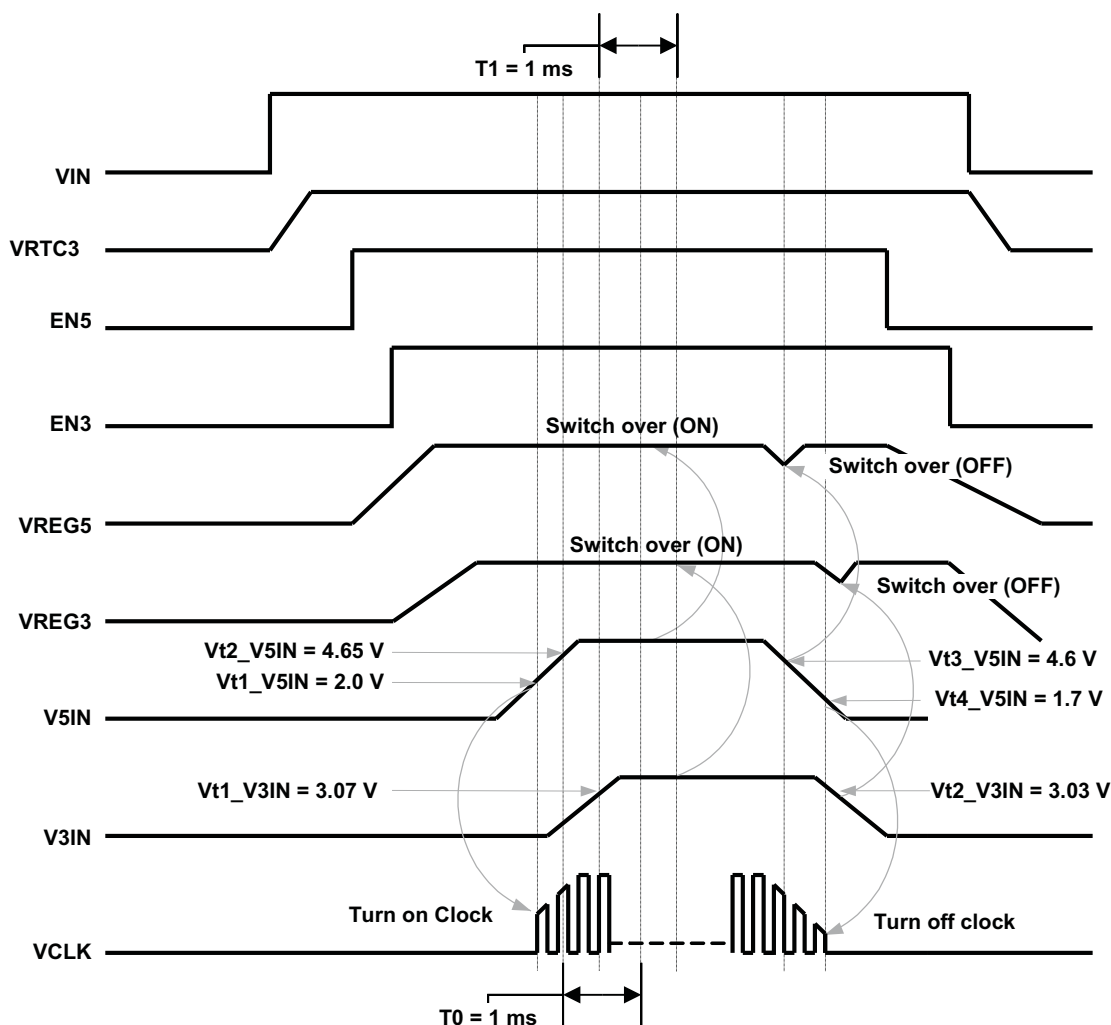


TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
EN3	5	I	3.3-V LDO enable input.
EN5	4	I	5-V LDO enable input.
GND	2	–	Ground.
V3IN	6	I	3.3-V switchover power supply input. Switchover occurs 1 ms after this input voltage reaches the threshold voltage.
V5IN	10	I	5-V switchover power supply input. Switchover occurs 1 ms after this input voltage reaches to threshold voltage.
VCLK	1	O	50% duty 250-kHz clock output for charge pump power supply.
VIN	8	I	Power supply input for LDOs.
VREG3	7	O	3.3-V 100 mA LDO output.
VREG5	9	O	5-V 100 mA LDO output.
VRTC3	3	O	3.3-V 5 mA always on LDO output for RTC.

FUNCTIONAL BLOCK DIAGRAM





UDG-08016

Figure 1. Power Sequencing

DETAILED DESCRIPTION

GENERAL DESCRIPTION

The TPS51103 integrates three LDOs. The VREG5 and VREG3 can each deliver 100 mA of current. The device includes glitch free switch-over circuits which turn off VREG5 and VREG3 LDOs and switch VREG5 and VREG3 to V5IN and V3IN external power inputs respectively when the external high efficiency 5V and 3.3V power rails are available. It improves overall system efficiency and therefore extends battery life. An additional 5-mA VRTC3 LDO is designed to provide an *always on* feature for the real time clock (RTC). A 5-V clock with 50% duty cycle runs at 250 kHz. It can be used as a simple external charge pump driver to generate a 10-V or 15-V low-current voltage rail (see Figure 2). In the notebook application, the 10 V or 15 V created by this circuit could be used to drive an N-channel MOSFET instead of the traditional P-channel MOSFET load switch. The TPS51103 boosts performance and reduce the cost of load switch.

VREG5

When EN5 is asserted high, VREG5 supplies 5 V through an LDO from V_{IN} . Its maximum sourcing current is 100 mA. If EN5 is high and the V5IN voltage becomes higher than 4.65 V, then the VREG5 output is switched over to the V5IN input after a 1-ms delay. In the switched over condition, the LDO is turned off and VREG5 is connected to V5IN through the 1.0- Ω $R_{DS(on)}$ MOSFET switch. When the V5IN voltage becomes lower than 4.6 V, this MOSFET turns off and 5-V LDO is turned back on immediately. A bypass ceramic capacitor is required to stabilize LDO. The recommended value is between 10 μ F and 22 μ F. Place the bypass capacitor close to the VREG5 pin. When EN5 is asserted low, both the 5-V LDO and switchover circuit are turned off.

VREG3

When EN3 is asserted high, VREG3 supplies 3.3 V through an LDO from V_{IN} . Its maximum sourcing current is 100 mA. If EN3 is high and the V3IN voltage becomes higher than 3.07 V, then the VREG3 output is switched over to the V3IN input after a 1-ms delay. In the switched over condition, LDO is turned off and VREG3 is connected to V3IN through the 1.5- Ω $R_{DS(on)}$ MOSFET switch. When the V3IN voltage becomes lower than 3.03 V, this MOSFET turns off and the 3.3-V LDO is turned back on immediately. A bypass ceramic capacitor is needed to stabilize LDO, recommended value is between 10 μ F and 22 μ F. Place the bypass capacitor close to the VREG3 pin. When EN3 is asserted low, both the 3.3-V LDO and the switchover circuit are turned off.

VRTC3

This 3.3-V low-current auxiliary power source is typically used for the system's RTC bias voltage. It is powered on after V_{IN} is applied. A ceramic capacitor with a value between 1 μ F and 2.2 μ F placed close to the VRTC3 pin is needed to stabilize the LDO.

VCLK OUTPUT

When the V5IN voltage becomes higher than 2.0 V, the internal 250-kHz clock turns on and the VCLK pin outputs a 50% duty-cycle clock signal. The voltage swing of VCLK is equal to the GND to V5IN voltage

THERMAL SHUTDOWN

When the device temperature exceeds the internal threshold value (typically 150°C) the TPS51103 shuts off the VREG3, VREG5 and VCLK outputs. This is a non-latch protection.

THERMAL DESIGN

The thermal performance greatly depends on the printed circuit board (PCB) layout. The TPS51103 is housed in a thermally-enhanced PowerPAD™ package that has an exposed die pad underneath the body. For improved thermal performance, this die pad must be attached to ground via thermal land on the PCB. This ground trace acts as a heatsink and a heat spreader. For further information regarding the PowerPAD™ package and the recommended board layout, refer to the PowerPAD™ package application note (SLMA002). This document is available at www.ti.com.

LAYOUT GUIDELINES

Consider the following points before starting the TPS51103 layout design.

- The input bypass capacitor for V_{IN} should be placed as close as possible to the pin with short and wide connection.
- The output capacitors for VREG5, VREG3 and VRTC3 should be placed close to the pins with short and wide connections.
- In order to effectively remove heat from the package, properly prepare the thermal land. Apply solder directly to the package thermal pad. Wide copper traces connected to the thermal land help to dissipate heat. Numerous 0.33 mm diameter vias are connected from the thermal land to the internal and/or solder-side system ground plane(s) can also be used to help dissipation.
- The GND pin, output capacitors for VREG5, VREG3 and VRTC3 should be connected to the internal and/or solder-side system ground plane(s) with multiple vias. Use as many vias as possible to reduce the impedance between them and the system ground plane.

APPLICATION INFORMATION

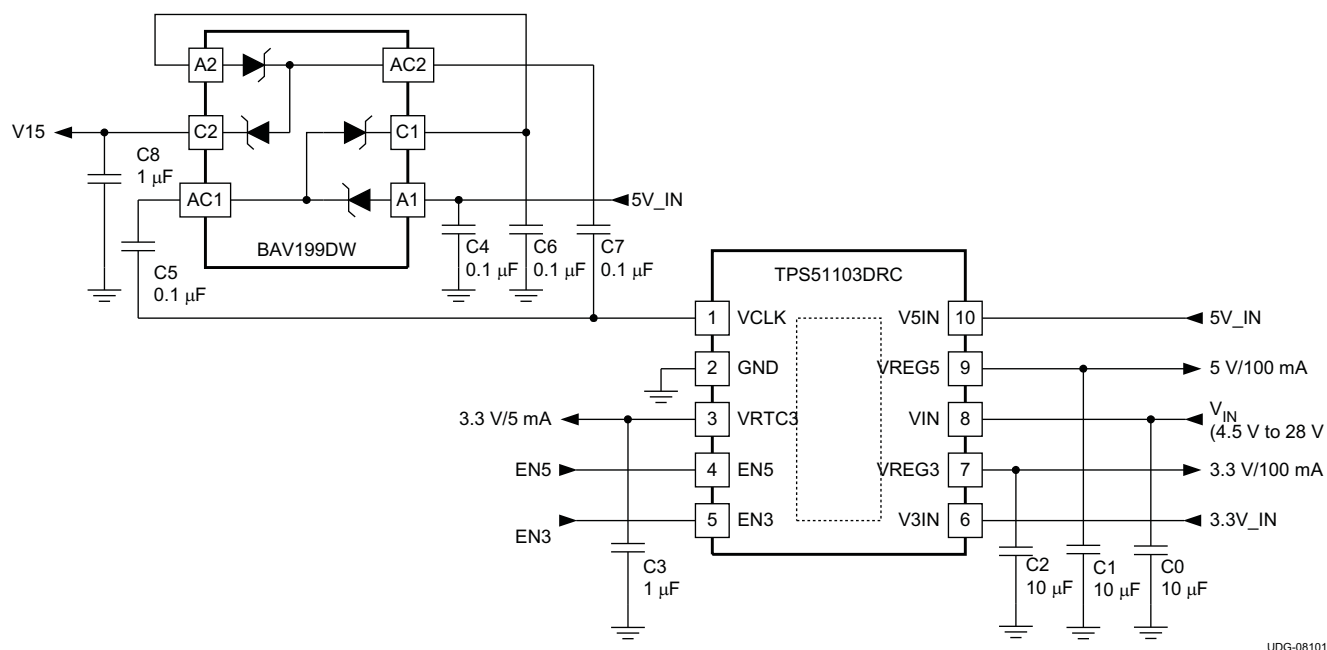


Figure 2. Typical Application

TYPICAL CHARACTERISTICS

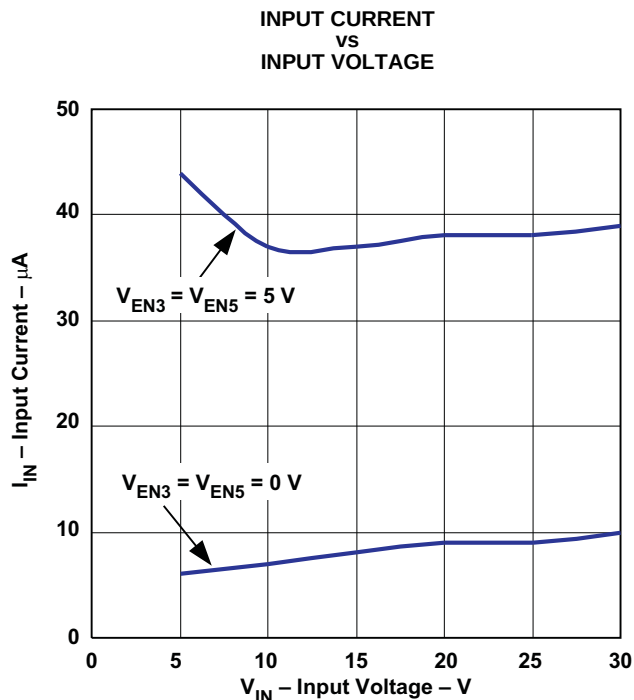


Figure 3.

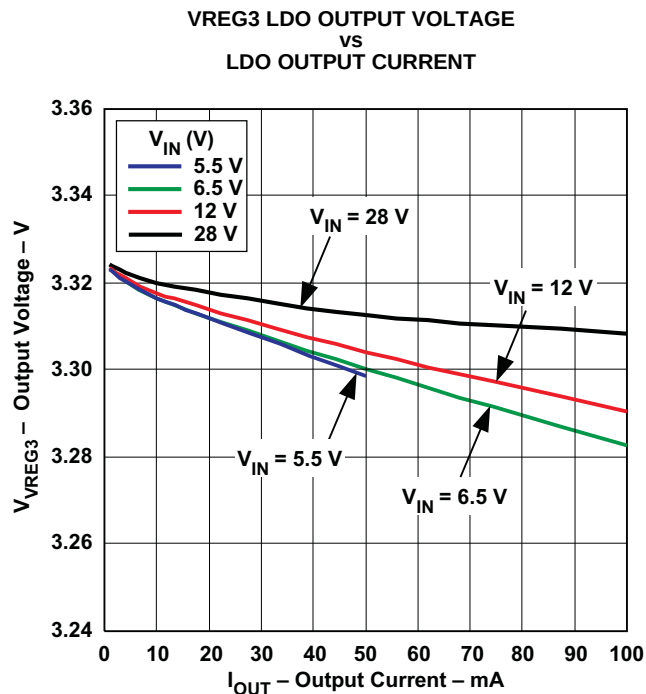


Figure 4.

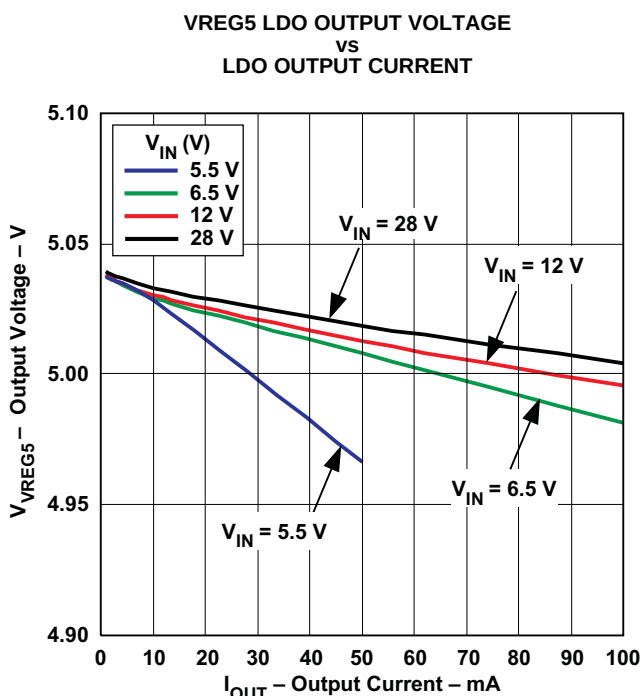


Figure 5.

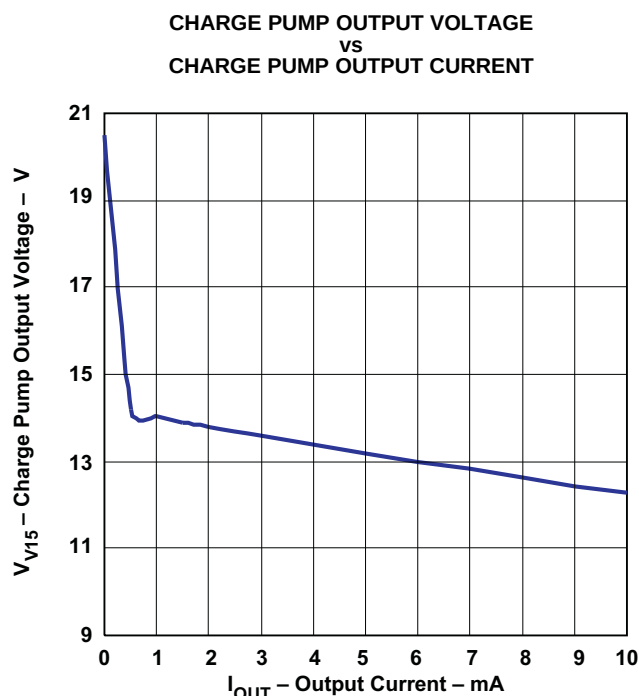


Figure 6.

TYPICAL CHARACTERISTICS (continued)

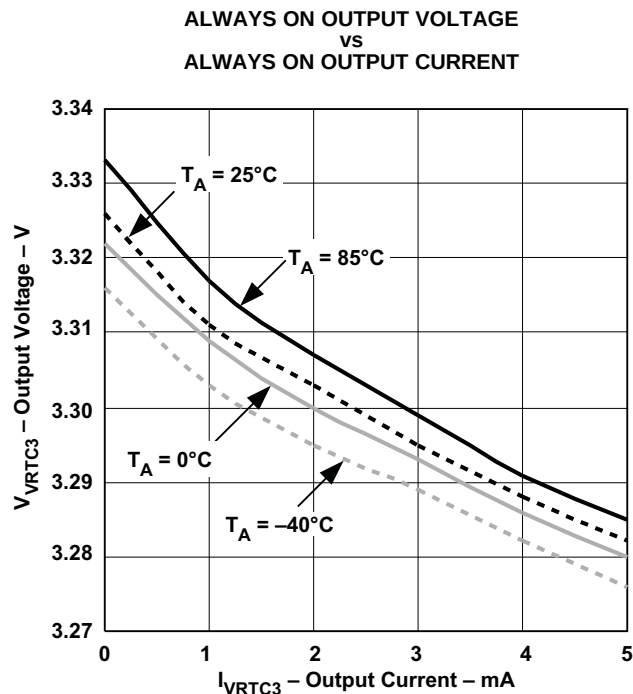


Figure 7.

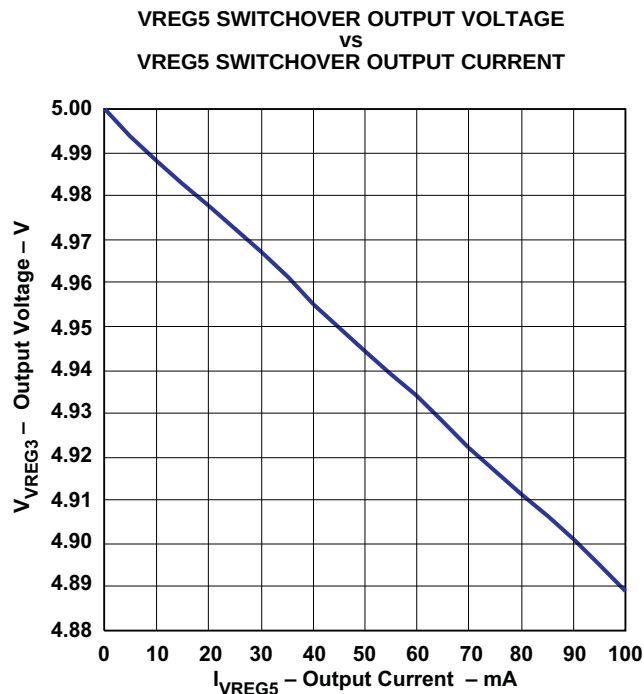


Figure 8.

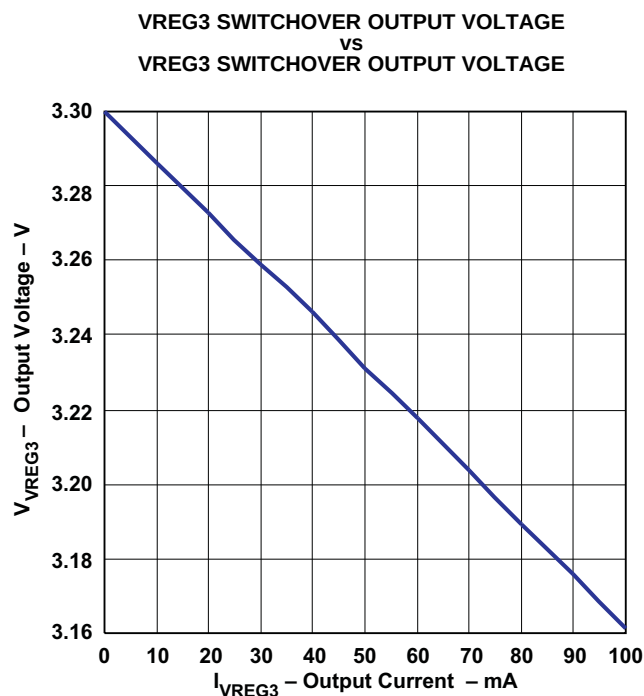


Figure 9.

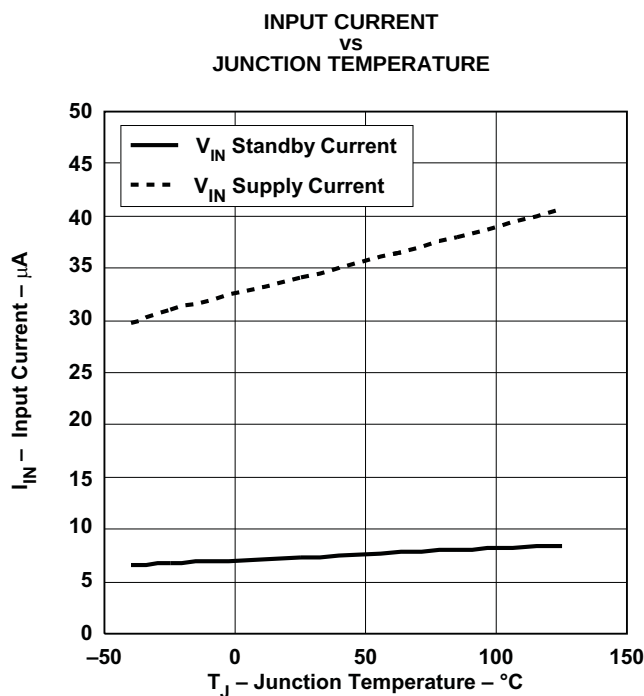


Figure 10.

TYPICAL CHARACTERISTICS (continued)

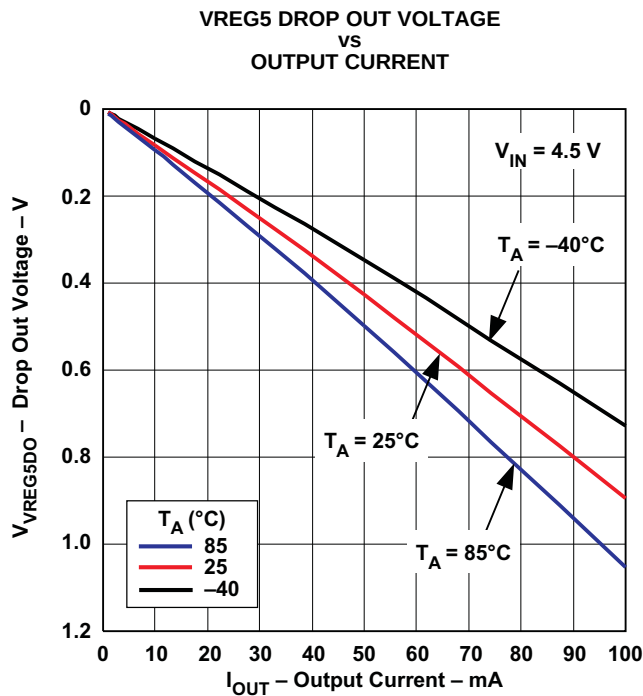


Figure 11.

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS

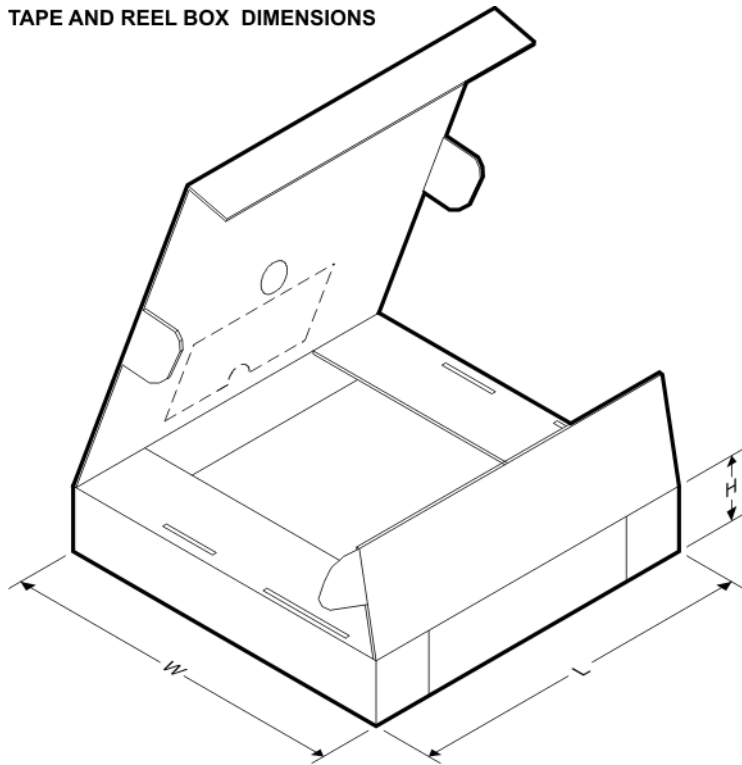

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS51103DRCR	SON	DRC	10	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TPS51103DRCT	SON	DRC	10	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS

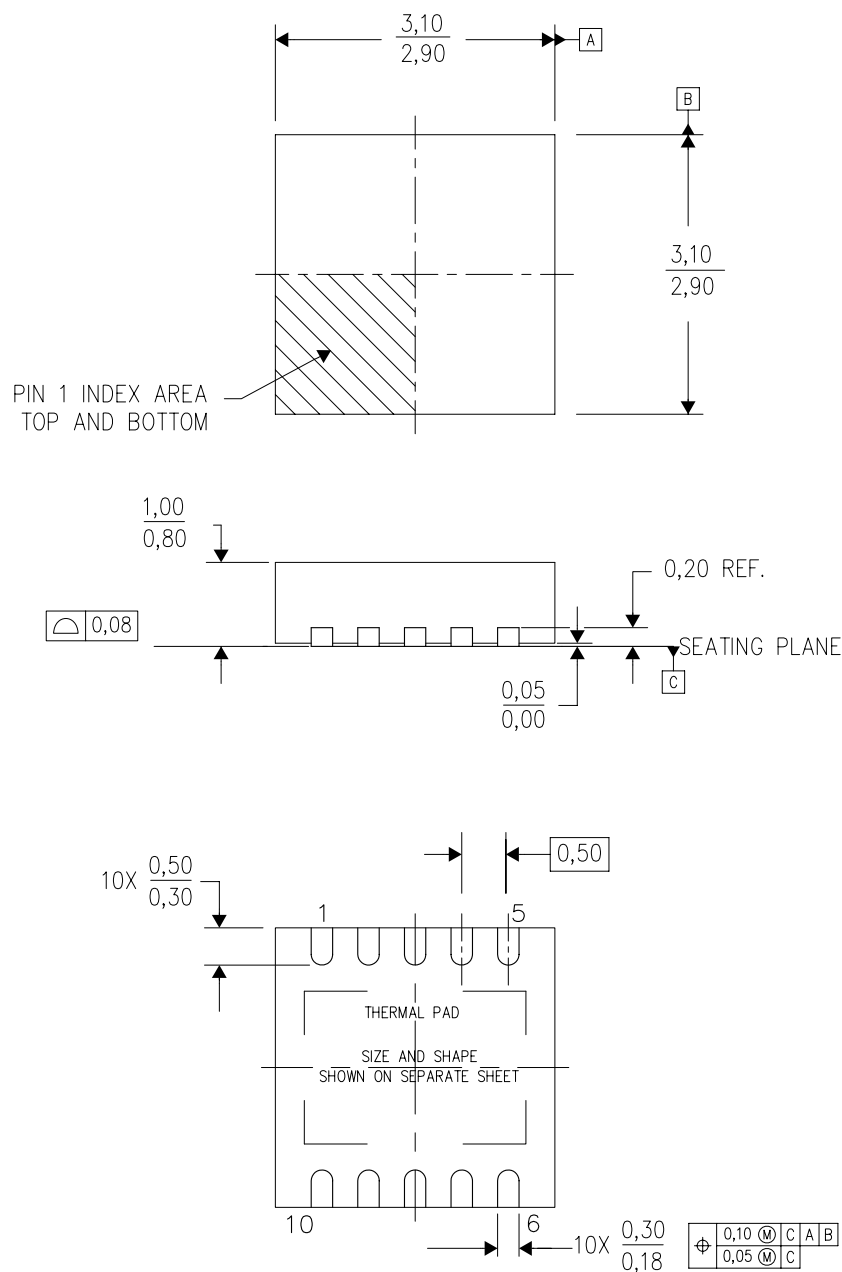


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS51103DRCR	SON	DRC	10	3000	367.0	367.0	35.0
TPS51103DRCT	SON	DRC	10	250	210.0	185.0	35.0

DRC (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



4204102-3/L 09/11

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Small Outline No-Lead (SON) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance, if present.
 - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions, if present

DRC (S-PVSON-N10)

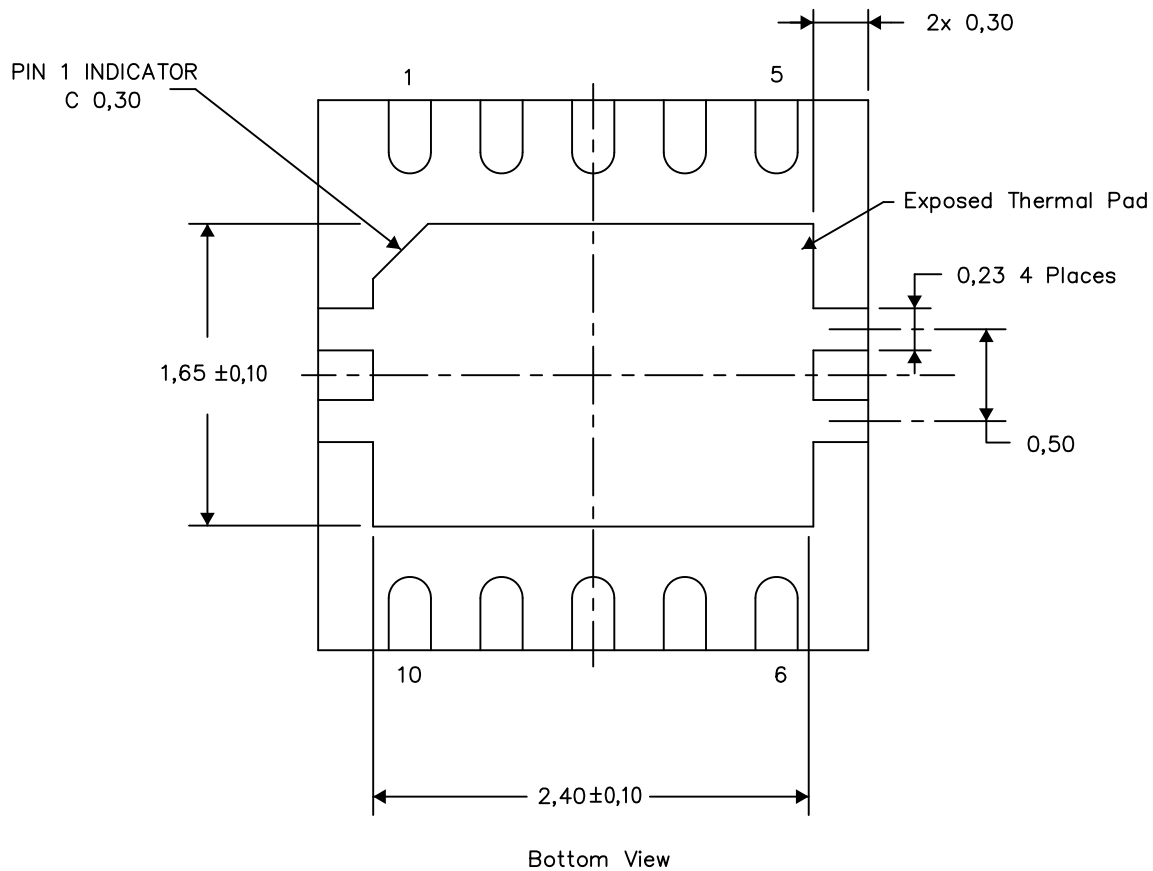
PLASTIC SMALL OUTLINE NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



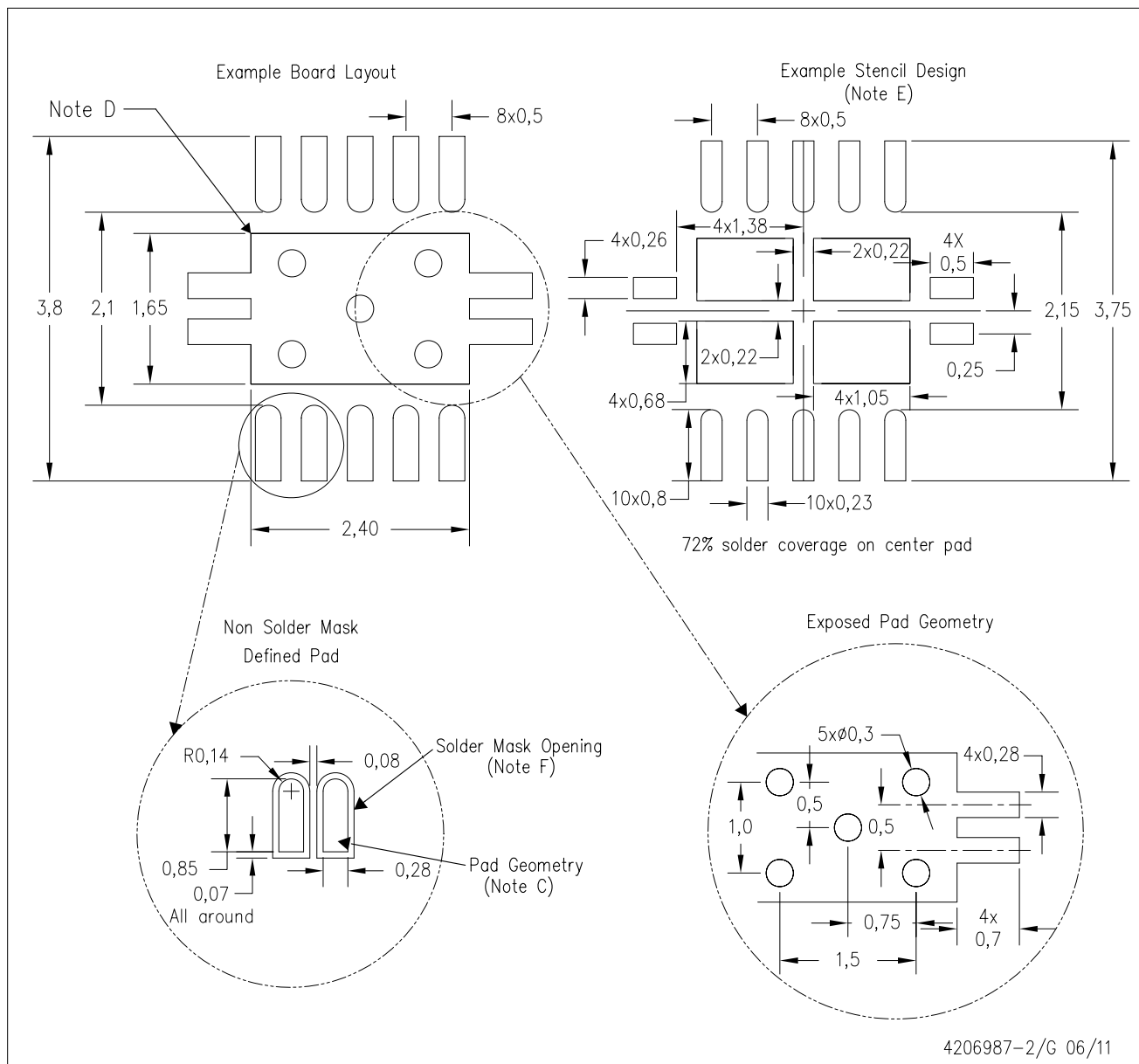
Exposed Thermal Pad Dimensions

4206565-3/N 07/12

NOTE: A. All linear dimensions are in millimeters

DRC (S-PVSON-N10)

PLASTIC SMALL OUTLINE NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com